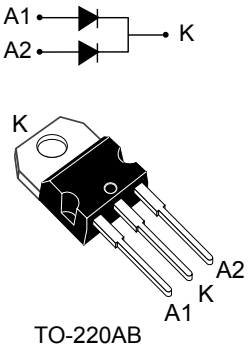
STPS16150C

Datasheet

150 V power Schottky rectifier



TO-220AB

Features

- High junction temperature capability
- Good trade-off between leakage current and forward voltage drop
- Low leakage current
- Avalanche capability rated
- ECOPACK®2 compliant

Applications

- Switching diode
- SMPS
- DC/DC converter
- LED lighting

Description

The STPS16150C is a dual center tap Schottky rectifier suited for high frequency switch mode power supply.

Available in TO-220AB, this device is optimized for use in LCD screens or adaptors providing such applications with good efficiency at both low and high load.

Product status link
STPS16150C

Product summary	
$I_{F(AV)}$	2 x 8 A
V_{RRM}	150 V
T_j	175 °C
V_F (typ.)	0.70 V

1 Characteristics

Table 1. Absolute ratings (limiting values per diode at 25 °C, unless otherwise specified)

Symbol	Parameter			Value	Unit
V_{RRM}	Repetitive peak reverse voltage			150	V
$I_{F(RMS)}$	Forward rms current			20	A
$I_{F(AV)}$	Average forward current, δ = 0.5, square wave	T_c = 150 °C	Per diode	8	A
			Per device	16	
I_{FSM}	Surge non repetitive forward current	t_p = 10 ms sinusoidal		150	A
P_{ARM}	Repetitive peak avalanche power	t_p = 10 µs, T_j = 125 °C		338	W
T_{stg}	Storage temperature range			-65 to +175	°C
T_j	Maximum operating junction temperature (1)			175	°C

1. *$(dP_{tot}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.*

Table 2. Thermal resistance parameters

Symbol	Parameter		Max. value	Unit
$R_{th(j-c)}$	Junction to case	Per diode	3	°C/W
		Total	1.8	
$R_{th(c)}$	Coupling		0.6	°C/W

When the diodes 1 and 2 are used simultaneously: $\Delta T_{j\ (diode1)} = P_{(diode1)} \times R_{th(j-c)}$ (per diode) + $P_{(diode2)} \times R_{th(c)}$

For more information, please refer to the following application note :

- AN5088 : Rectifiers thermal management, handling and mounting recommendations

Table 3. Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I_R (1)	Reverse leakage current	T_j = 25 °C	$V_R = V_{RRM}$	-		3.0	µA
		T_j = 125 °C		-		4.0	mA
V_F (2)	Forward voltage drop	T_j = 25 °C	I_F = 8 A	-		0.92	V
		T_j = 125 °C		-	0.70	0.75	
		T_j = 25 °C	I_F = 16 A	-		1	
		T_j = 125 °C		-	0.80	0.86	

1. *Pulse test: t_p = 5 ms, δ < 2%*
2. *Pulse test: t_p =380 µs, δ < 2%*

To evaluate the conduction losses, use the following equation:

$P = 0.64 \times I_{F(AV)} + 0.014 \times I_F{}^2{}_{(RMS)}$

For more information, please refer to the following application notes related to the power losses :

- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

1.1 Characteristics (curves)

Figure 1. Average forward power dissipation versus average forward current (per diode)

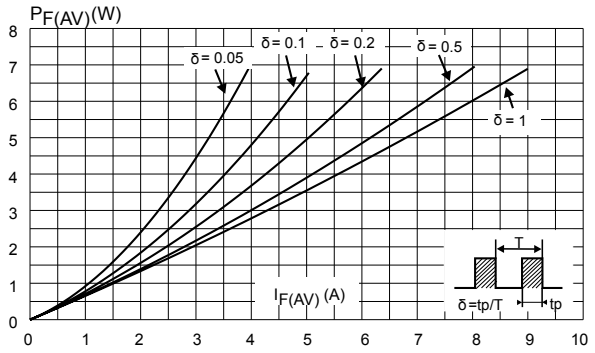


Figure 2. Average forward current versus ambient temperature (δ = 0.5, per diode)

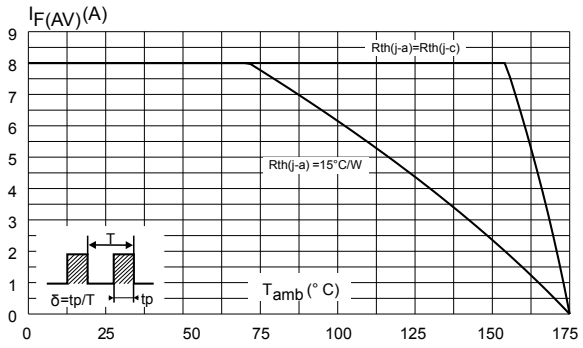


Figure 3. Normalized avalanche power derating versus pulse duration (T_j = 125 °C)

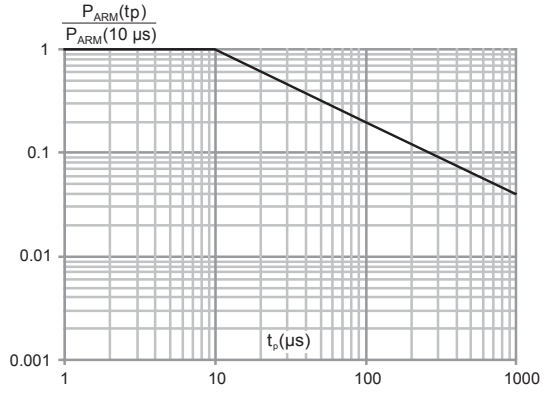


Figure 4. Relative variation of thermal impedance junction to case versus pulse duration

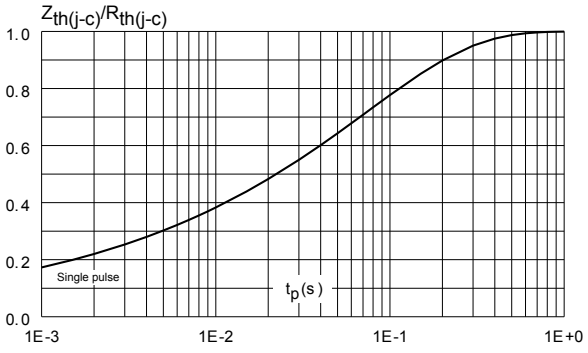


Figure 5. Reverse leakage current versus reverse voltage applied (typical values, per diode)

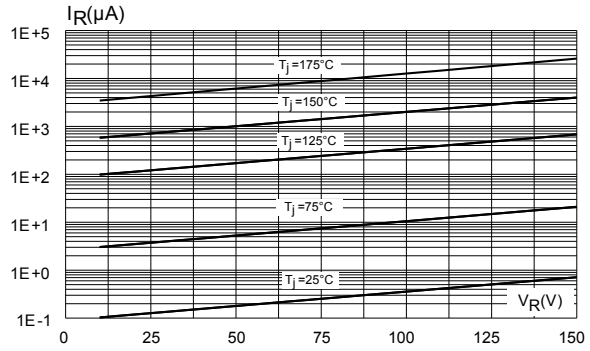


Figure 6. Junction capacitance versus reverse voltage applied (typical values, per diode)

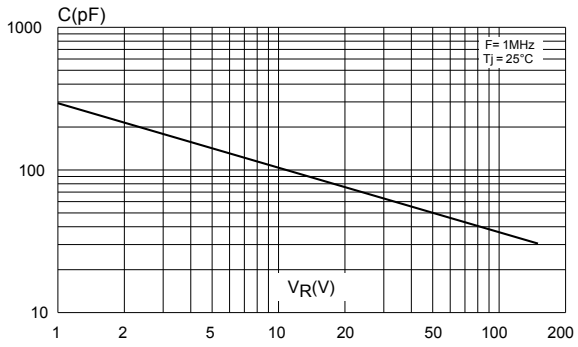
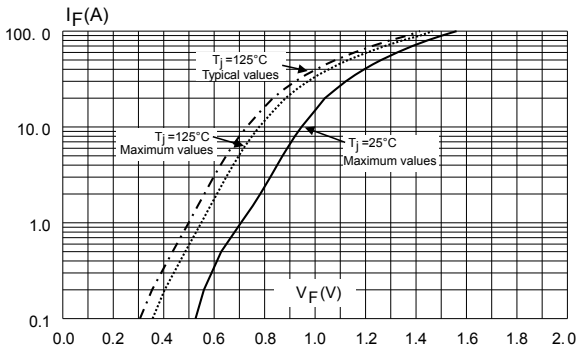


Figure 7. Forward voltage drop versus forward current (per diode)



2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

2.1 TO220AB package information

- Epoxy meets UL 94,V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.55 N·m
- Maximum torque value: 0.70 N·m

Figure 8. TO-220AB package outline

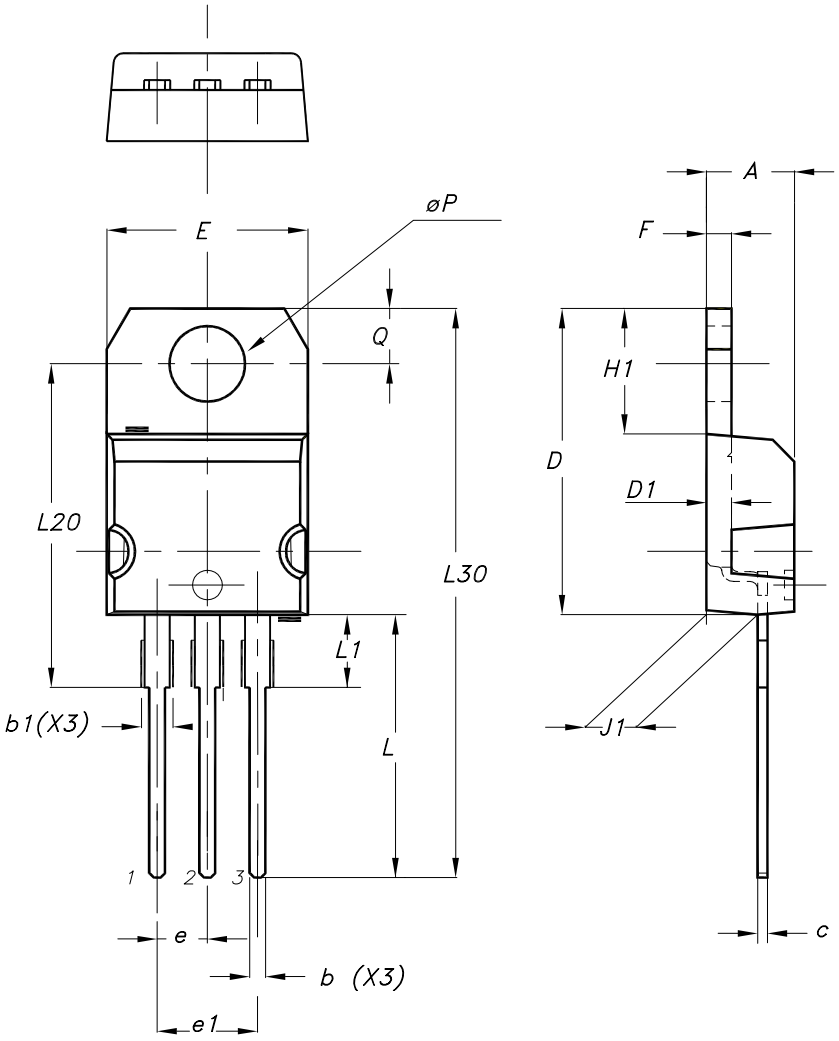


Table 4. TO-220AB package mechanical data

Ref.	Dimensions			
	Millimeters		Inches (for reference only)	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
b	0.61	0.88	0.240	0.035
b1	1.14	1.55	0.045	0.061
c	0.48	0.70	0.019	0.028
D	15.25	15.75	0.600	0.620
D1	1.27 typ.		0.050 typ.	
E	10.00	10.40	0.394	0.409
e	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.195	0.203
F	1.23	1.32	0.048	0.052
H1	6.20	6.60	0.244	0.260
J1	2.40	2.72	0.094	0.107
L	13.00	14.00	0.512	0.551
L1	3.50	3.93	0.138	0.155
L20	16.40 typ.		0.646 typ.	
L30	28.90 typ.		1.138 typ.	
θP	3.75	3.85	0.148	0.152
Q	2.65	2.95	0.104	0.116

3 Ordering information

Table 5. **Order code**

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS16150CT	STPS16150CT	TO-220AB	1.95 g	50	Tube

Revision history

Table 6. **Document revision history**

Date	Revision	Changes
July-2003	2	First issue.
17-Aug-2018	3	Removed I²PAK and D²PAK packages. Removed figure 4, figure 5 and figure 10. Updated Section 1.1 Characteristics (curves). Updated cover page and Table 1. Minor text changes to improve readability.

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